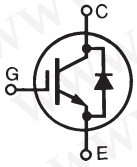
IXYS

HiPerFAST™ IGBT with Diode

IXGH40N60C2D1
IXGT40N60C2D1
IXGJ40N60C2D1

V_{CES} = 600V
I_{C25} = 75A
$V_{CE(SAT)}$ ≤ 2.7V
$t_{fi(typ)}$ = 32ns

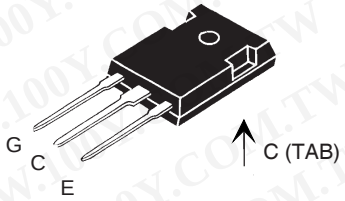
C2-Class High Speed IGBTs



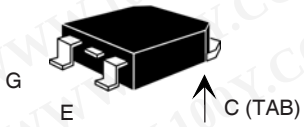
Symbol	Test Conditions	Maximum Ratings	
V_{CES}	T_J = 25°C to 150°C	600	V
V_{CGR}	T_J = 25°C to 150°C, R_{GE} = 1MΩ	600	V
V_{GES}	Continuous	±20	V
V_{GEM}	Transient	±30	V
I_{C25}	T_C = 25°C (limited by leads)	75	A
I_{C110}	T_C = 110°C	40	A
I_{CM}	T_C = 25°C, 1 ms	200	A
SSOA (RBSOA)	V_{GE} = 15V, T_{VJ} = 125°C, R_G = 10Ω Clamped inductive load @ V_{CE} ≤ 600V	I_{CM} = 80	A
P_C	T_C = 25°C	300	W
T_J		-55 ... +150	°C
T_{JM}		150	°C
T_{stg}		-55 ... +150	°C
T_L	Maximum lead temperature for soldering	300	°C
T_{SOLD}	1.6mm (0.062 in.) from case for 10s	260	°C
M_d	Mounting torque (IXGH)	1.13/10	Nm/lb.in
F_C	Mounting force (IXGJ)	20..120/4.5..27	N/lb
Weight	TO-247	6	g
	TO-268 types	5	g

Symbol	Test Conditions	Characteristic Values (T_J = 25°C unless otherwise specified) Min.	Typ.	Max.	
$V_{GE(th)}$	I_C = 250μA, V_{CE} = V_{GE}	3.0		5.0	V
I_{CES}	V_{CE} = V_{CES}, V_{GE} = 0V			200	μA
		T_J = 125°C		3	mA
I_{GES}	V_{CE} = 0V, V_{GE} = ±20V			±100	nA
$V_{CE(sat)}$	I_C = 30A, V_{GE} = 15V, Note 1		2.2	2.7	V
		T_J = 125°C	1.7		V

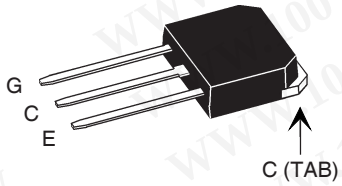
TO-247(IXGH)



TO-268 (D3) (IXGT)



TO-268 Leaded (IXGJ)



G = Gate C = Collector
E = Emitter

Features

- Very high frequency IGBT
- Square RBSOA
- High current handling capability
- MOS Gate turn-on
  - drive simplicity

Applications

- Uninterruptible power supplies (UPS)
- Switched-mode and resonant-mode power supplies
- AC motor speed control
- DC servo and robot drives
- DC choppers

Advantages

- High power density
- Very fast switching speeds for high frequency applications
- High power surface mountable packages

IXYS

IXGH40N60C2D1 IXGT40N60C2D1 IXGJ40N60C2D1

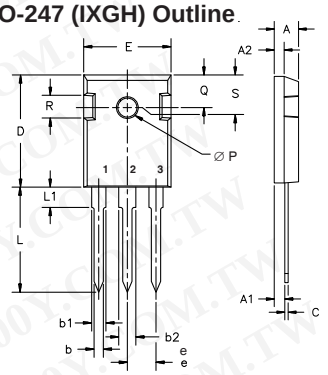
Symbol	Test Conditions (T_J = 25°C unless otherwise specified)	Characteristic Values Min.	Typ.	Max.	
g_{fs}	I_C = 30A, V_{CE} = 10V, Note 1	20	36		S
C_{ies}	V_{CE} = 25V, V_{GE} = 0V, f = 1 MHz		2500		pF
C_{oes}			220		pF
C_{res}			54		pF
Q_g	I_C = 30A, V_{GE} = 15V, V_{CE} = 0.5 • V_{CES}		95		nC
Q_{ge}			14		nC
Q_{gc}			36		nC
$t_{d(on)}$	**Inductive load, T_J = 125°C**		18		ns
t_{ri}	I_C = 30A, V_{GE} = 15V		20		ns
$t_{d(off)}$	V_{CE} = 400V, R_G = 3Ω		90	140	ns
t_{fi}			32		ns
E_{off}			0.20	0.37	mJ
$t_{d(on)}$	**Inductive load, T_J = 125°C**		18		ns
t_{ri}	I_C = 30A, V_{GE} = 15V		20		ns
E_{on}	V_{CE} = 400V, R_G = 3Ω		0.6		mJ
$t_{d(off)}$			130		ns
t_{fi}			80	240	ns
E_{off}			0.50		mJ
R_{thJC}				0.42	°C/W
R_{thCK}	(IXGH, IXGJ)		0.25		°C/W

Reverse Diode (FRED)

Symbol	Test Conditions (T_J = 25°C, unless otherwise specified)	Characteristic Values Min.	Typ.	Max.	
V_F	I_F = 30A, V_{GE} = 0V, Pulse test T_J =150°C			1.6	V
				2.5	V
I_{RM}	I_F = 30A, V_{GE} = 0V, -di_F/dt =100A/µs, T_J = 100°C			4	A
t_{rr}	V_R = 100V T_J = 100°C		100		ns
	I_F = 1A, -di/dt = 100A/µs, V_R = 30V		25		ns
R_{thJC}				0.9	°C/W

Note 1: Pulse test, t ≤ 300µs; duty cycle, d ≤ 2 %.

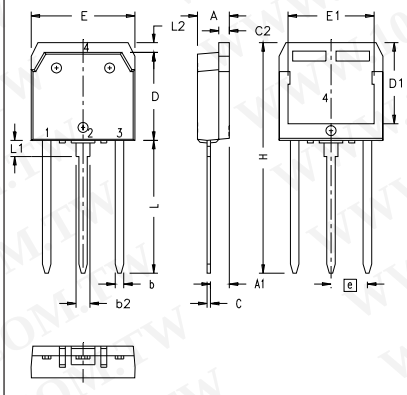
TO-247 (IXGH) Outline



Terminals: 1 - Gate 2 - Drain
3 - Source Tab - Drain

Dim.	Millimeter Min.	Max.	Inches Min.	Max.
A	4.7	5.3	.185	.209
A_1	2.2	2.54	.087	.102
A_2	2.2	2.6	.059	.098
b	1.0	1.4	.040	.055
b_1	1.65	2.13	.065	.084
b_2	2.87	3.12	.113	.123
C	.4	.8	.016	.031
D	20.80	21.46	.819	.845
E	15.75	16.26	.610	.640
e	5.20	5.72	0.205	0.225
L	19.81	20.32	.780	.800
L1		4.50		.177
ØP	3.55	3.65	.140	.144
Q	5.89	6.40	0.232	0.252
R	4.32	5.49	.170	.216
S	6.15 BSC		242 BSC	

TO-268 Leaded Outline

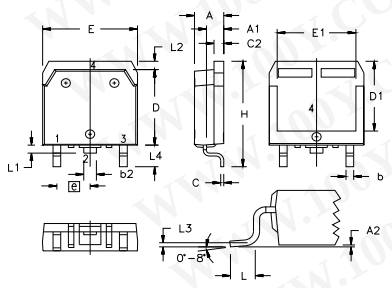


SYM	INCHES MIN	MAX	MILLIMETERS MIN	MAX
A	.193	.201	4.90	5.10
A1	.106	.114	2.70	2.90
b	.045	.057	1.15	1.45
b2	.075	.083	1.90	2.10
C	.016	.026	0.40	0.65
C2	.057	.063	1.45	1.60
D	.543	.551	13.80	14.00
D1	.488	.500	12.40	12.70
E	.624	.632	15.85	16.05
E1	.524	.535	13.30	13.60
e	.215 BSC		5.45 BSC	
H	1.365	1.395	34.67	35.43
L	.780	.800	19.81	20.32
L1	.079	.091	2.00	2.30
L2	.039	.045	1.00	1.15

NOTE: ALL METAL AREA ARE SOLDER PLATED.

1 – GATE
2 – DRAIN (COLLECTOR)
3 – SOURCE (EMITTER)
4 – DRAIN (COLLECTOR)

TO-268 Outline



SYM	INCHES MIN	MAX	MILLIMETERS MIN	MAX
A	.193	.201	4.90	5.10
A1	.106	.114	2.70	2.90
A2	.001	.010	0.02	0.25
b	.045	.057	1.15	1.45
b2	.075	.083	1.90	2.10
C	.016	.026	0.40	0.65
C2	.057	.063	1.45	1.60
D	.543	.551	13.80	14.00
D1	.488	.500	12.40	12.70
E	.624	.632	15.85	16.05
E1	.524	.535	13.30	13.60
e	.215 BSC		5.45 BSC	
H	.736	.752	18.70	19.10
L	.094	.106	2.40	2.70
L1	.047	.055	1.20	1.40
L2	.039	.045	1.00	1.15
L3	.010 BSC		0.25 BSC	
L4	.150	.161	3.80	4.10

IXYS reserves the right to change limits, test conditions, and dimensions.

IXYS MOSFETs and IGBTs are covered by one or more of the following U.S. patents: 4,835,592 4,850,072 4,881,106 4,931,844 5,017,508 5,034,796 5,049,961 5,063,307 5,187,117 5,237,481 5,381,025 5,486,715 6,162,665 6,259,123 B1 6,306,728 B1 6,404,065 B1 6,534,343 6,583,505 6,683,344 6,710,405 B2 6,710,463 6,727,585 6,759,692 6,771,478 B2 7,005,734 B2 7,063,975 B2 7,071,537 7,157,338B2

Fig. 1. Output Characteristics
@ 25 Deg. C

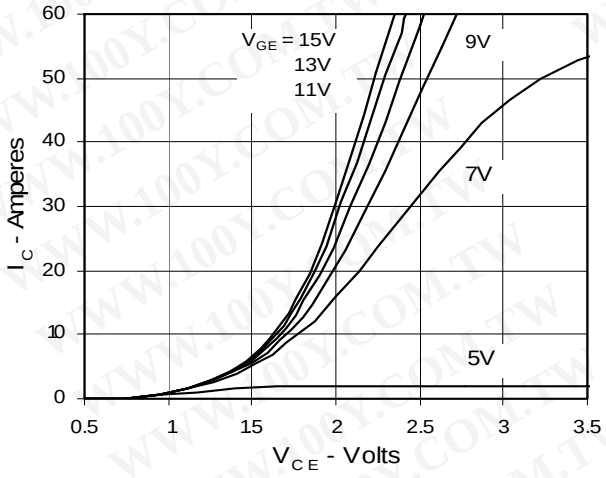


Fig. 2. Extended Output Characteristics
@ 25 deg. C

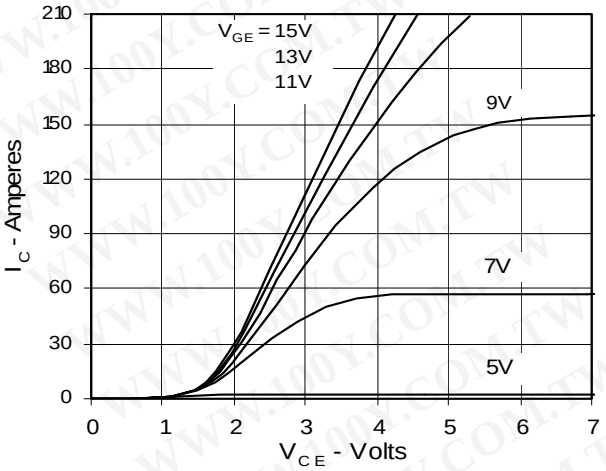


Fig. 3. Output Characteristics
@ 125 Deg. C

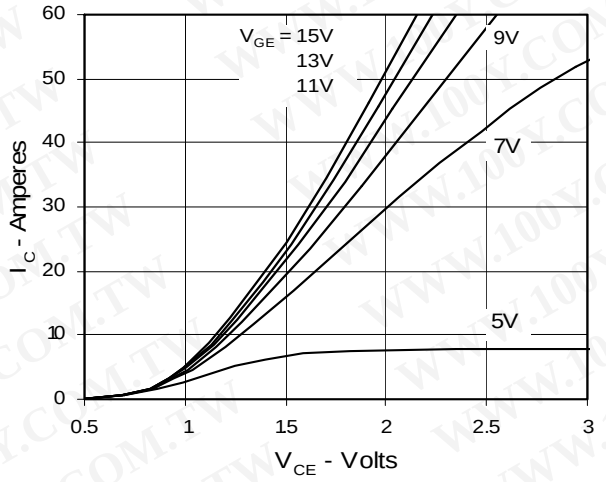


Fig. 4. Temperature Dependence of $V_{CE(sat)}$

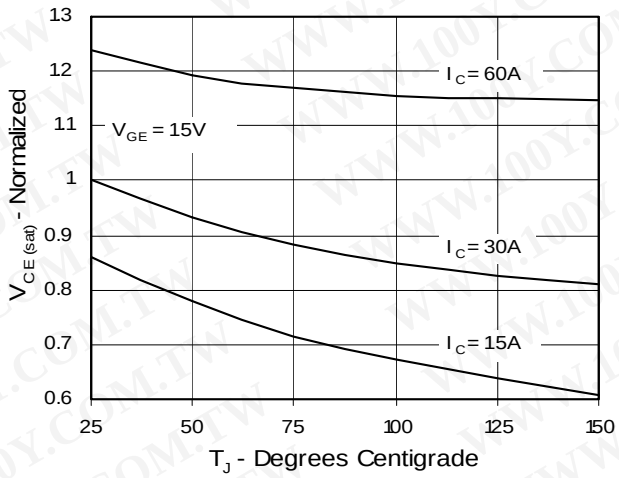


Fig. 5. Collector-to-Emitter Voltage
vs. Gate-to-Emitter voltage

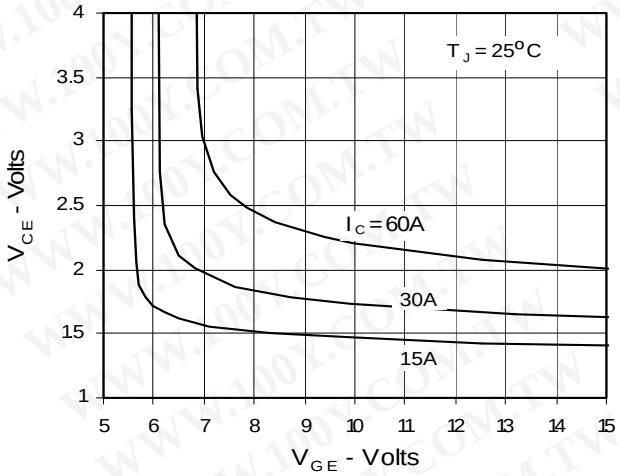


Fig. 6. Input Admittance

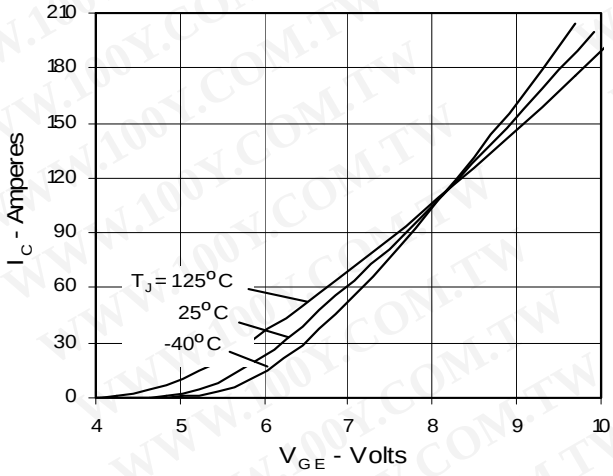


Fig. 7. Transconductance

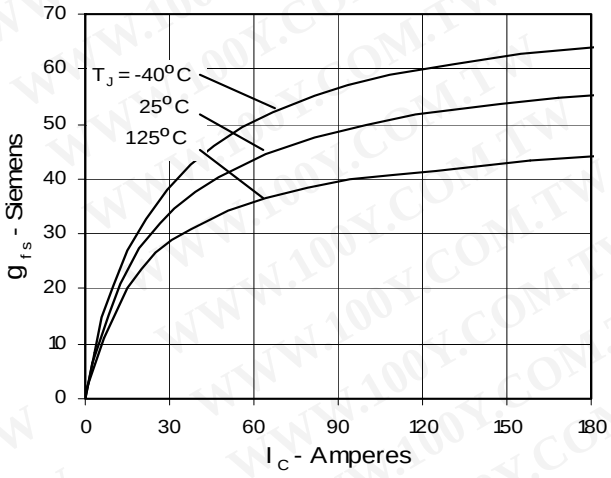


Fig. 8. Dependence of E_{off} on R_G

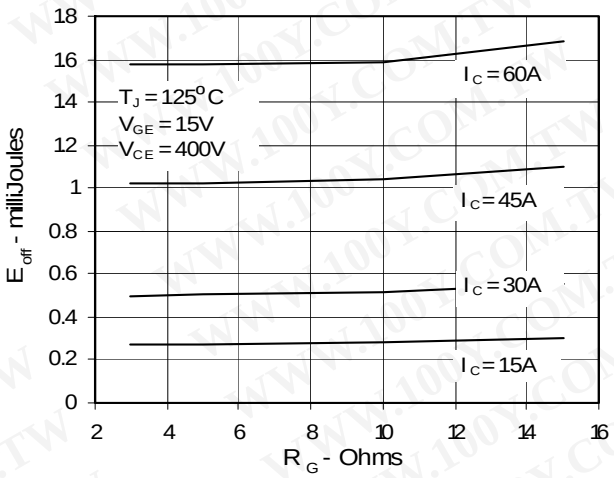


Fig. 9. Dependence of E_{off} on I_C

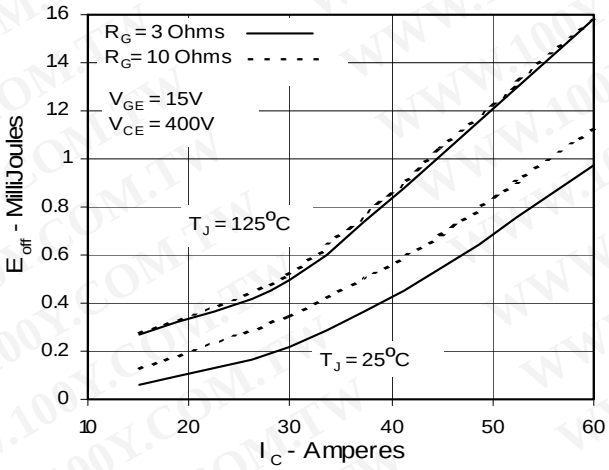


Fig. 10. Dependence of E_{off} on Temperature

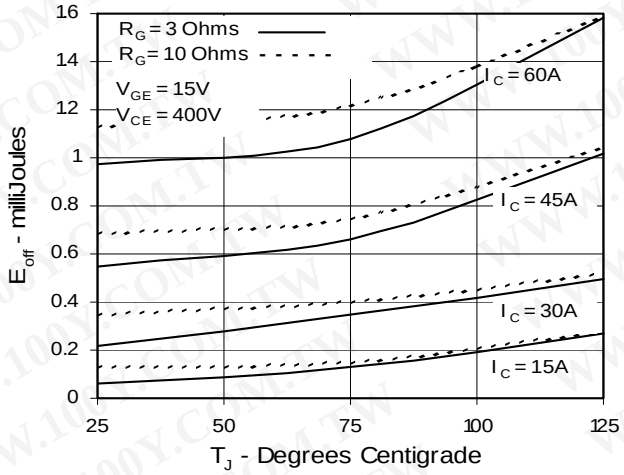


Fig. 11. Gate Charge

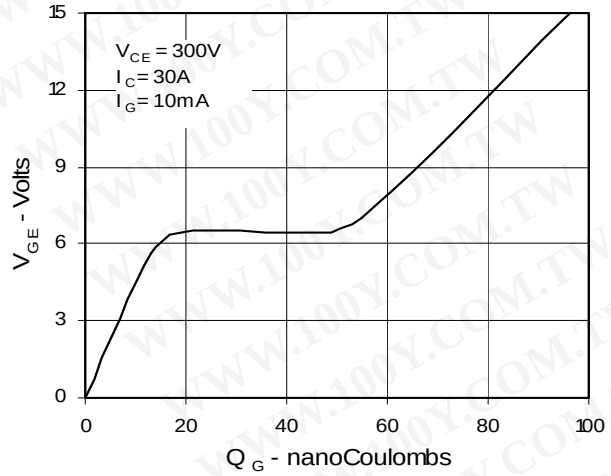


Fig. 12. Capacitance

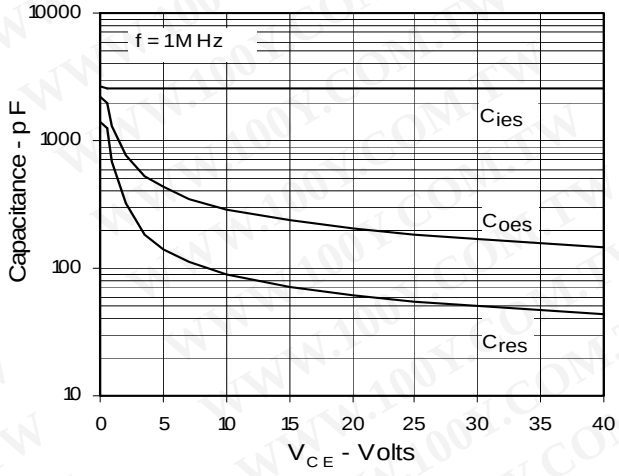
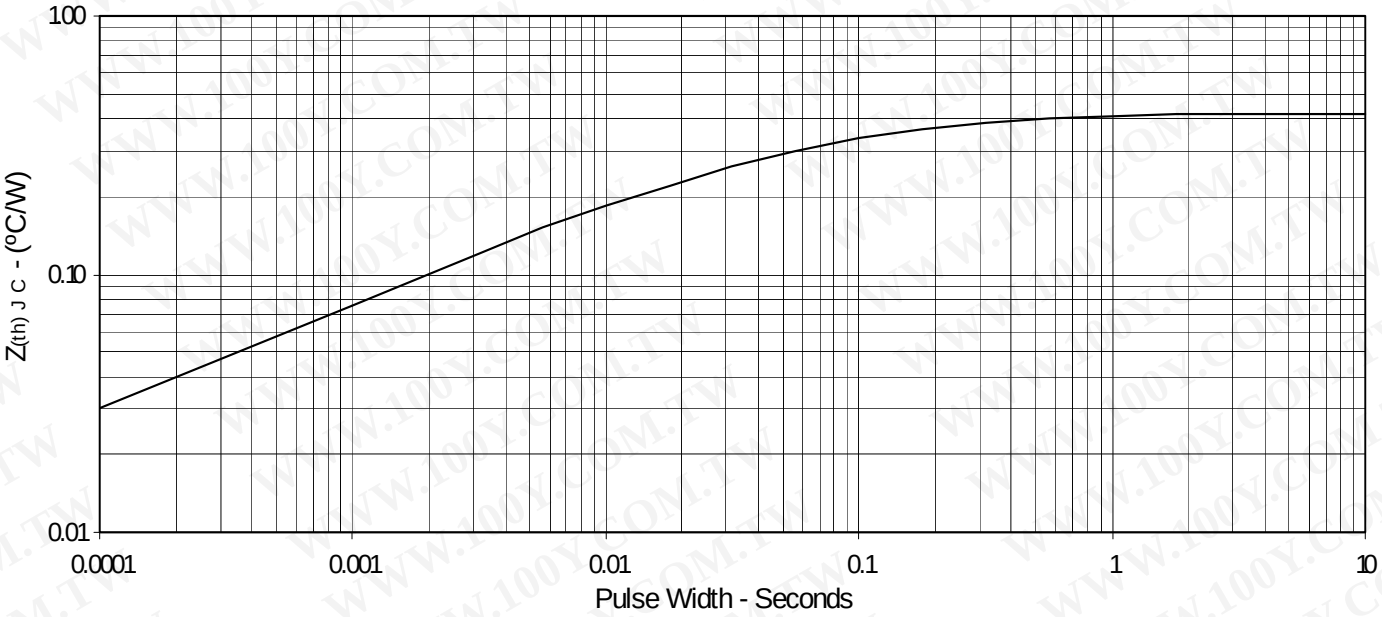


Fig. 13. Maximum Transient Thermal Impedance



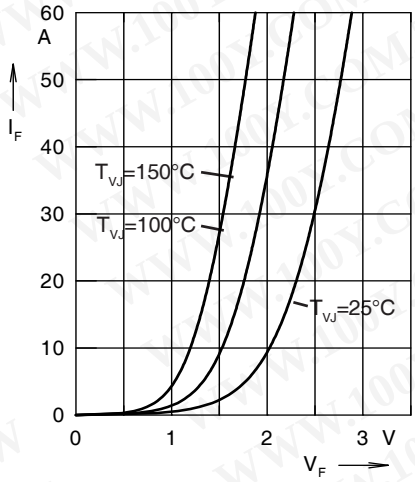


Fig. 14. Forward current I_F versus V_F

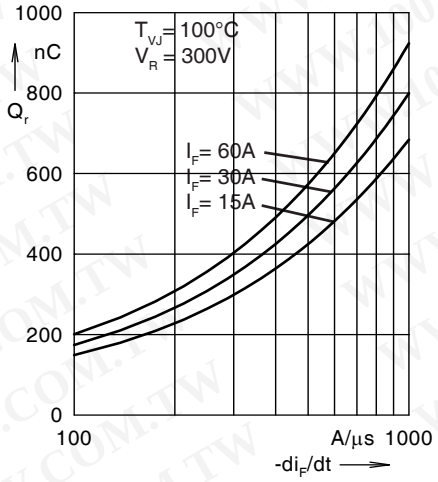


Fig. 15. Reverse recovery charge Q_r versus -di_F/dt

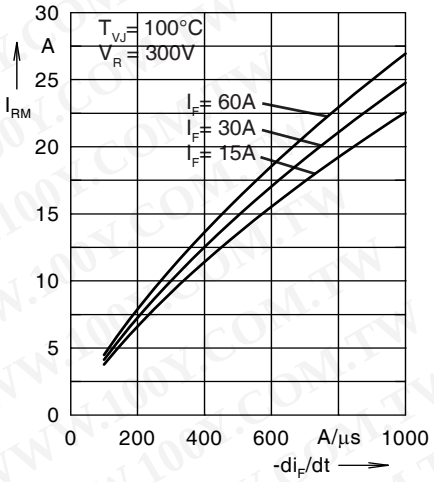


Fig. 16. Peak reverse current I_{RM} versus -di_F/dt

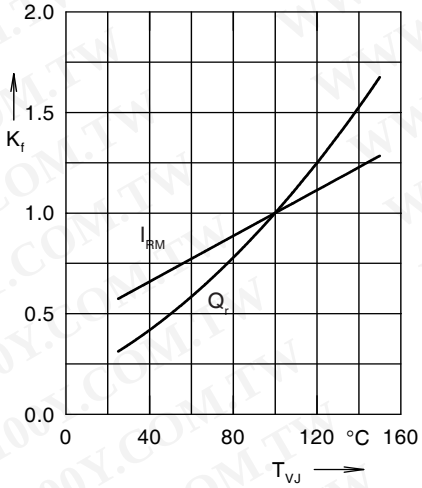


Fig. 17. Dynamic parameters Q_r, I_{RM} versus T_{VJ}

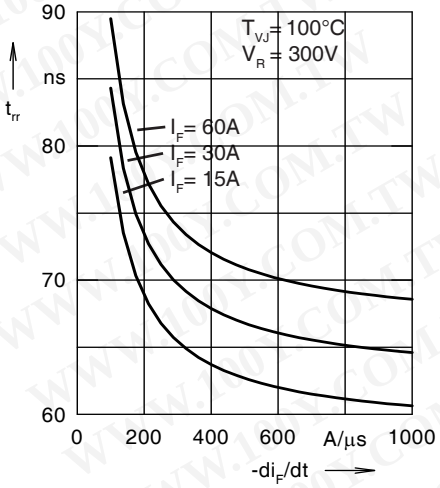


Fig. 18. Recovery time t_{rr} versus -di_F/dt

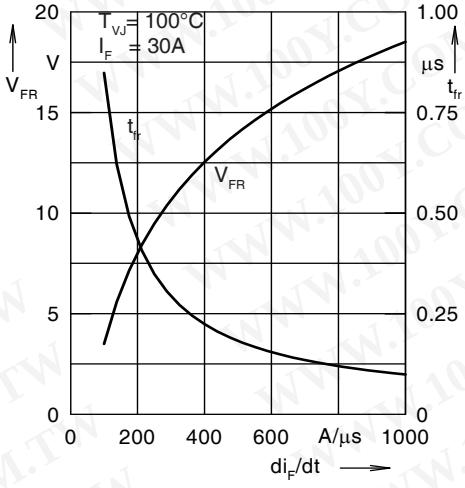


Fig. 19. Peak forward voltage V_{FR} and t_{fr} versus di_F/dt

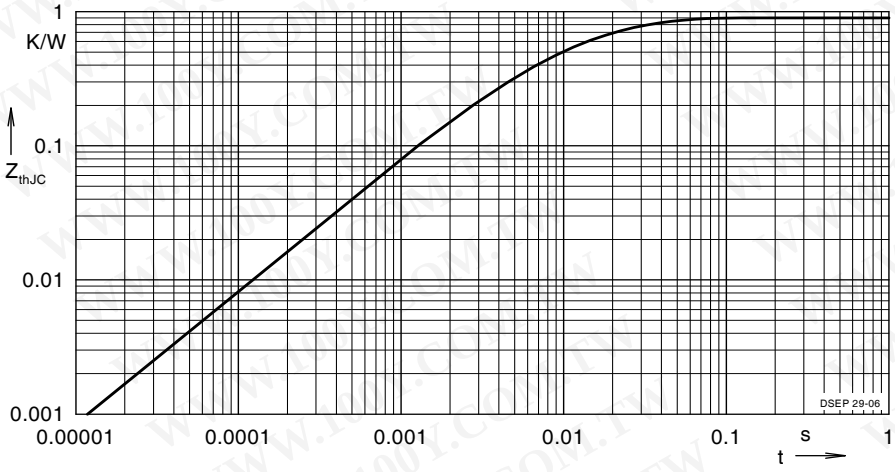


Fig. 20. Transient thermal resistance junction to case

Constants for Z_{thJC} calculation:

i	R_{thi} (K/W)	t_i (s)
1	0.502	0.0052
2	0.193	0.0003
3	0.205	0.0162